



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





High Performance Sensorless Motor Control IC

Description

IRMCK171 is a high performance One Time Programmable ROM based motion control IC designed and optimized for appliance control which contains two computation engines integrated into one monolithic chip. One is the Flexible Motion Control Engine (MCE™) for sensorless control of permanent magnet motors or induction motors; the other is an 8-bit high-speed microcontroller (8051). The user can program a motion control algorithm by connecting these control elements using a graphic compiler. Key components of the complex sensorless control algorithms, such as the Angle Estimator, are provided as complete pre-defined control blocks. A unique analog/digital circuit and algorithm fully supports single shunt or leg shunt current reconstruction. IRMCK171 comes in a 48 pin QFP package.

Features

- MCE™ (Flexible Motion Control Engine) - Dedicated computation engine for high efficiency sinusoidal sensorless motor control
- Built-in hardware peripheral for single or two shunt current feedback reconstruction and analog circuits
- Supports induction machine and both interior and surface permanent magnet motor sensorless control
- Loss minimization Space Vector PWM
- Two-channel analog output (PWM)
- Embedded 8-bit high speed microcontroller (8051) for flexible I/O and man-machine control
- JTAG programming port for emulation/debugger
- Serial communication interface (UART)
- I2C/SPI serial interface
- Internal 32Kbyte OTP ROM
- 3.3V single supply

Product Summary

Maximum clock input (fcystal)	60
MHz	
Maximum Internal clock (SYSCLK)	128MHz
Maximum 8051 clock (8051CLK)	32MHz
MCE™ computation data range	16 bit
signed	
8051/MCE Data RAM	2KB
MCE Program RAM	12KB
PWM carrier frequency	20 bits/ SYSCLK
A/D input channels	7
A/D converter resolution	12 bits
A/D converter conversion speed	2 µsec
Analog output (PWM) resolution	8 bits
UART baud rate (typ)	57.6 Kbps
Number of digital I/O (max)	10
Package (lead free)	QFP48
Maximum 3.3V operating current	60mA

Base Part Number	Package Type	Standard Pack		Orderable Part Number
		Form	Quantity	
IRMCK171	QFP	Tray	2500	IRMCK171TY
		Tape and Reel	2000	IRMCK171TR

Table of Contents

1	Overview	5
2	Pinout	6
3	IRMCK171 Block Diagram and Main Functions	7
4	Application connection and Pin function	9
4.1	8051 Peripheral Interface Group	10
4.2	Motion Peripheral Interface Group	11
4.3	Analog Interface Group	11
4.4	Power Interface Group	11
4.5	Test Interface Group	11
5	DC Characteristics	13
5.1	Absolute Maximum Ratings	13
5.2	System Clock Frequency and Power Consumption	13
5.3	Digital I/O DC Characteristics	14
5.4	Analog I/O (IFB+,IFB-,IFBO, AIN5+,AIN5-,AIN5O) DC Characteristics	15
5.5	Under Voltage Lockout DC characteristics	16
5.6	Itrip comparator DC characteristics	16
5.7	CNEXT and AREF Characteristics	16
6	AC Characteristics	17
6.1	Digital PLL AC Characteristics	17
6.2	Analog to Digital Converter AC Characteristics	18
6.3	Op amp AC Characteristics	19
6.4	SYNC to SVPWM and A/D Conversion AC Timing	20
6.5	GATEKILL to SVPWM AC Timing	21
6.6	Itrip AC Timing	21
6.7	Interrupt AC Timing	22
6.8	I ² C AC Timing	22
6.9	SPI AC Timing	23
6.10	UART AC Timing	25
6.11	CAPTURE Input AC Timing	26
6.12	OTP Programming Timing	27
6.13	JTAG AC Timing	28
7	I/O Structure	29
8	Pin List	32
9	Package Dimensions	34
10	Part Marking Information	35
11	Qualification Information	35

List of Tables

Table 1 Absolute Maximum Ratings	13
Table 2 System Clock Frequency	13
Table 3 Digital I/O DC Characteristics	14
Table 5 Analog I/O DC Characteristics	15
Table 6 UVcc DC Characteristics	16
Table 7 Itrip DC Characteristics	16
Table 8 CMEXT and AREF DC Characteristics	16
Table 9 PLL AC Characteristics	17
Table 10 A/D Converter AC Characteristics	18
Table 11 Current Sensing OP Amp AC Characteristics	19
Table 12 SYNC AC Characteristics	20
Table 13 GATEKILL to SVPWM AC Timing	21
Table 14 Itrip AC Timing	21
Table 15 Interrupt AC Timing	22
Table 16 I ² C AC Timing	22
Table 17 SPI Write AC Timing	23
Table 18 SPI Read AC Timing	24
Table 19 UART AC Timing	25
Table 20 CAPTURE AC Timing	26
Table 21 OTP Programming Timing	27
Table 22 JTAG AC Timing	28
Table 23 Pin List	33

List of Figures

Figure 1 Typical Application Block Diagram Using IRMCK171	5
Figure 2 Pinout of IRMCK171	6
Figure 3 Crystal circuit example.....	17
Figure 4 Voltage droop and S/H hold time.....	18
Figure 5 A capacitor of 47pF is recommended at the output pin of all op amps.	19
Figure 6 SYNC timing	20
Figure 7 Gatekill timing	21
Figure 8 ITRIP timing	21
Figure 9 Interrupt timing	22
Figure 10 I ² C Timing	22
Figure 11 SPI write timing	23
Figure 12 SPI read timing	24
Figure 13 UART timing.....	25
Figure 14 CAPTURE timing	26
Figure 15 OTP programming timing.....	27
Figure 16 JTAG timing	28
Figure 17 PWMUL/PWMUH/PWMVL/PWMVH/PWMWL/PWMWH output.....	29
Figure 18 All digital I/O except motor PWM output.....	29
Figure 19 RESET, GATEKILL I/O.....	30
Figure 20 Analog input.....	30
Figure 21 Analog operational amplifier output and AREF I/O structure.....	30
Figure 22 VPP programming pin I/O structure.....	31
Figure 23 VSS and AVSS pin structure	31
Figure 24 VDD1 and VDDCAP pin structure	31
Figure 25 XTAL0/XTAL1 pins structure	31

1 Overview

IRMCK171 is a new generation International Rectifier integrated circuit device primarily designed as a one-chip solution for complete inverter controlled appliance motor control applications. Unlike a traditional microcontroller or DSP, the IRMCK171 provides a built-in closed loop sensorless control algorithm using the unique flexible Motion Control Engine (MCE™) for permanent magnet motors as well as induction motors. The MCE™ consists of a collection of control elements, motion peripherals, a dedicated motion control sequencer and dual port RAM to map internal signal nodes. IRMCK171 also employs a unique single shunt current reconstruction circuit in addition to two leg shunt current sensing circuit to eliminate additional analog/digital circuitry and enables a direct shunt resistor interface to the IC. Motion control programming is achieved using a dedicated graphical compiler integrated into the MATLAB/Simulink™ development environment. Sequencing, user interface, host communication, and upper layer control tasks can be implemented in the 8051 high-speed 8-bit microcontroller. The 8051 microcontroller is equipped with a JTAG port to facilitate emulation and debugging tools. Figure 1 shows a typical application schematic using the IRMCK171.

IRMCK171 contains 32K bytes of OTP program ROM, The IRMCF171 contains 64K bytes of Flash RAM and intended for development purposes only while the IRMCK171 is intended for volume production. Both the development and ROM versions come in a 48-pin QFP package with identical pin configuration to facilitate PC board layout and transition to mass production.

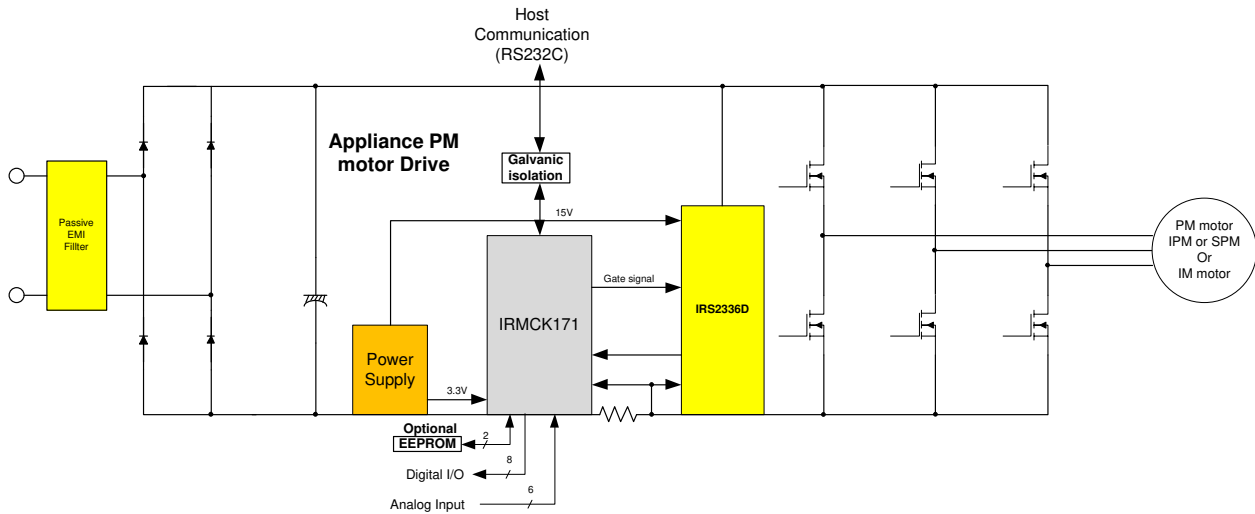


Figure 1 Typical Application Block Diagram Using IRMCK171

2 Pinout

Pin out shown is based on QFP48 pin package.

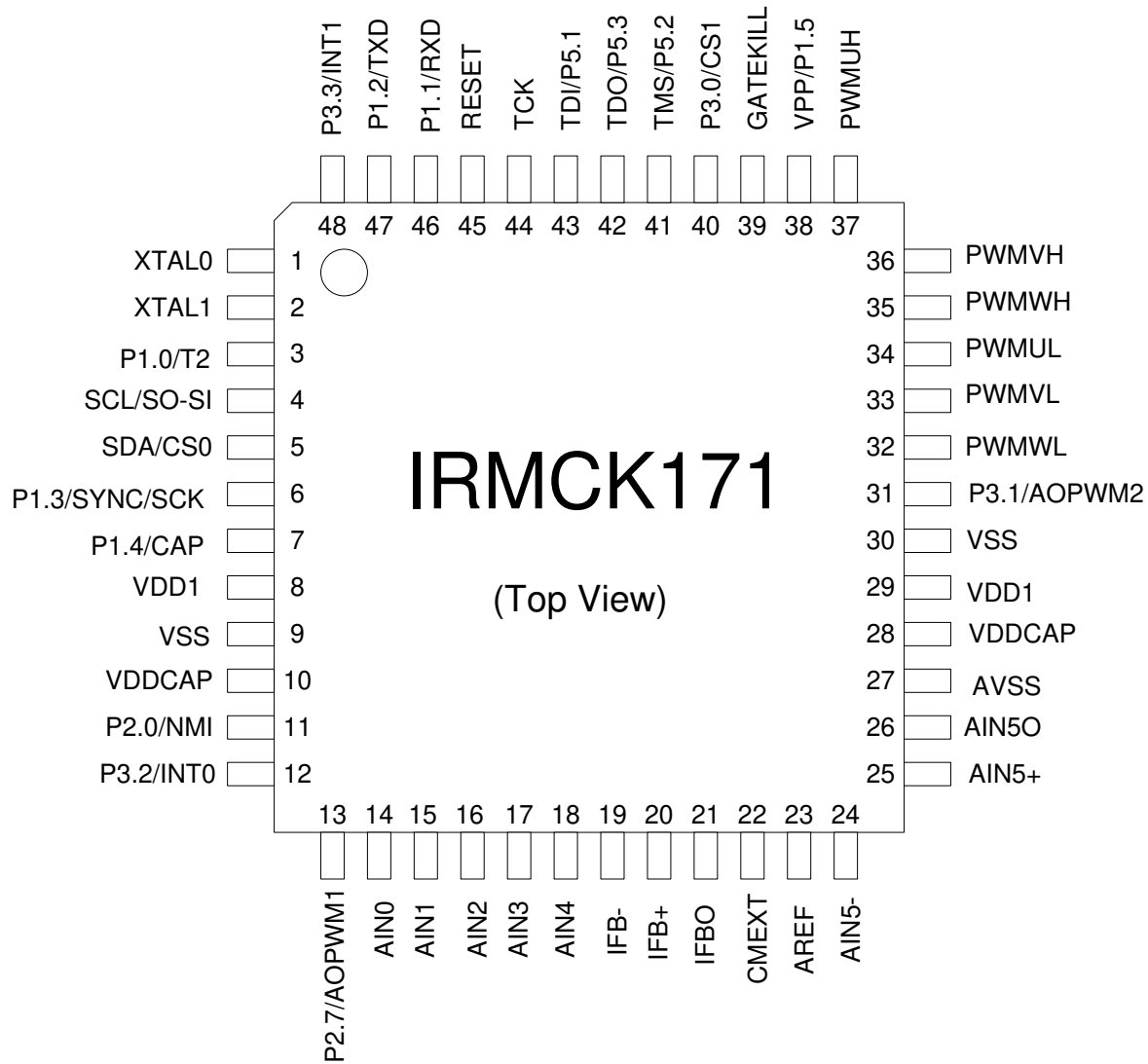


Figure 2 Pinout of IRMCK171

3 IRMCK171 Block Diagram and Main Functions

IRMCK171 block diagram is shown in Figure 3.

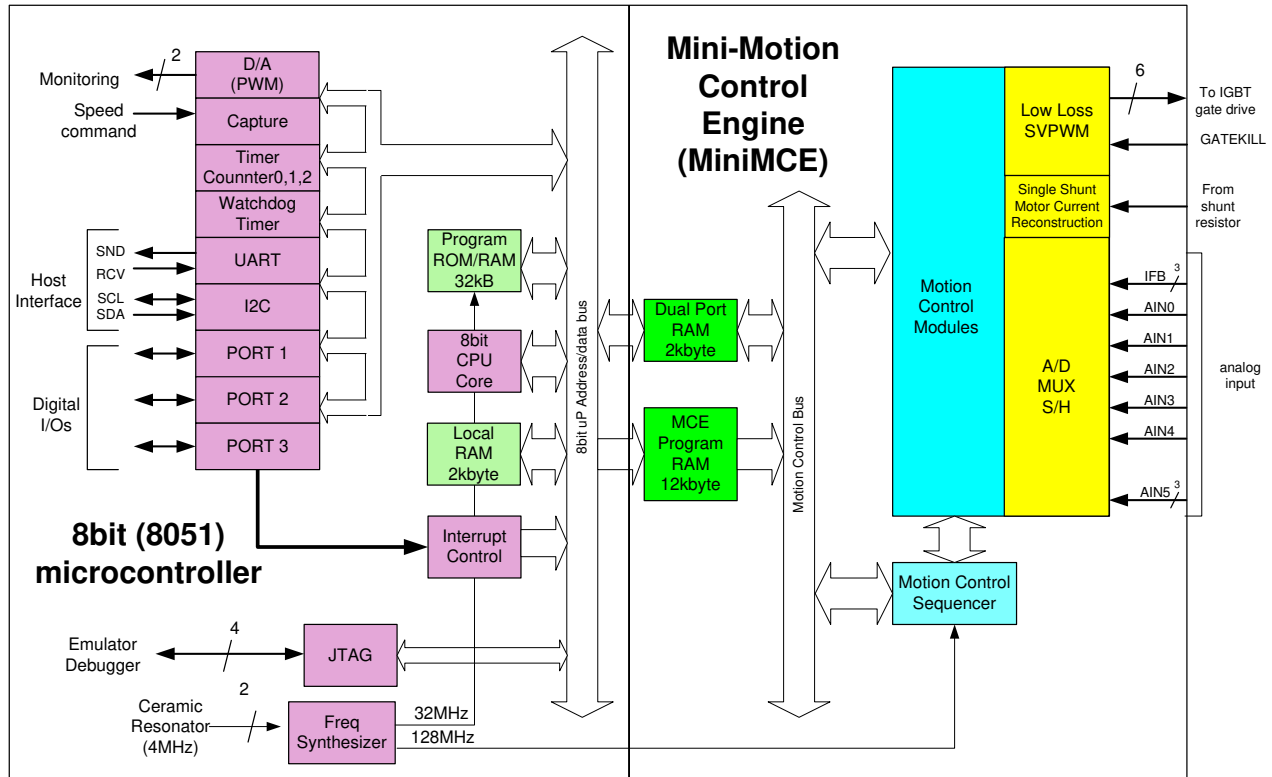


Figure 3 IRMCK171 Block Diagram

IRMCK171 contains the following functions for sensorless AC motor control applications:

- Motion Control Engine (MCE™)
 - Sensorless FOC (complete sensorless field oriented control)
 - Proportional plus Integral block
 - Low pass filter
 - Differentiator and lag (high pass filter)
 - Ramp
 - Limit
 - Angle estimate (sensorless control)
 - Inverse Clark transformation
 - Vector rotator
 - Bit latch
 - Peak detect

- Transition
- Multiply-divide (signed and unsigned)
- Divide (signed and unsigned)
- Adder
- Subtractor
- Comparator
- Counter
- Accumulator
- Switch
- Shift
- ATAN (arc tangent)
- Function block (any curve fitting, nonlinear function)
- 16 bit wide Logic operations (AND, OR, XOR, NOT, NEGATE)
- MCE™ program memory and dual port RAM (max 12K+2k byte)
- MCE™ control sequencer
- 8051 microcontroller
 - Two 16 bit timer/counters
 - One 16 bit periodic timer
 - One 16 bit watchdog timer
 - One 16 bit capture timer
 - Up to 24 discrete I/Os
 - Six-channel 12 bit A/D
 - Buffered (current sensing) one channel (0 – 1.2V input)
 - Unbuffered seven channels (0 – 1.2V input)
 - JTAG port (4 pins)
 - Up to three channels of analog output (8 bit PWM)
 - UART
 - I²C/SPI port
 - 32K byte OTP program ROM
 - 2K byte data RAM

4 Application connection and Pin function

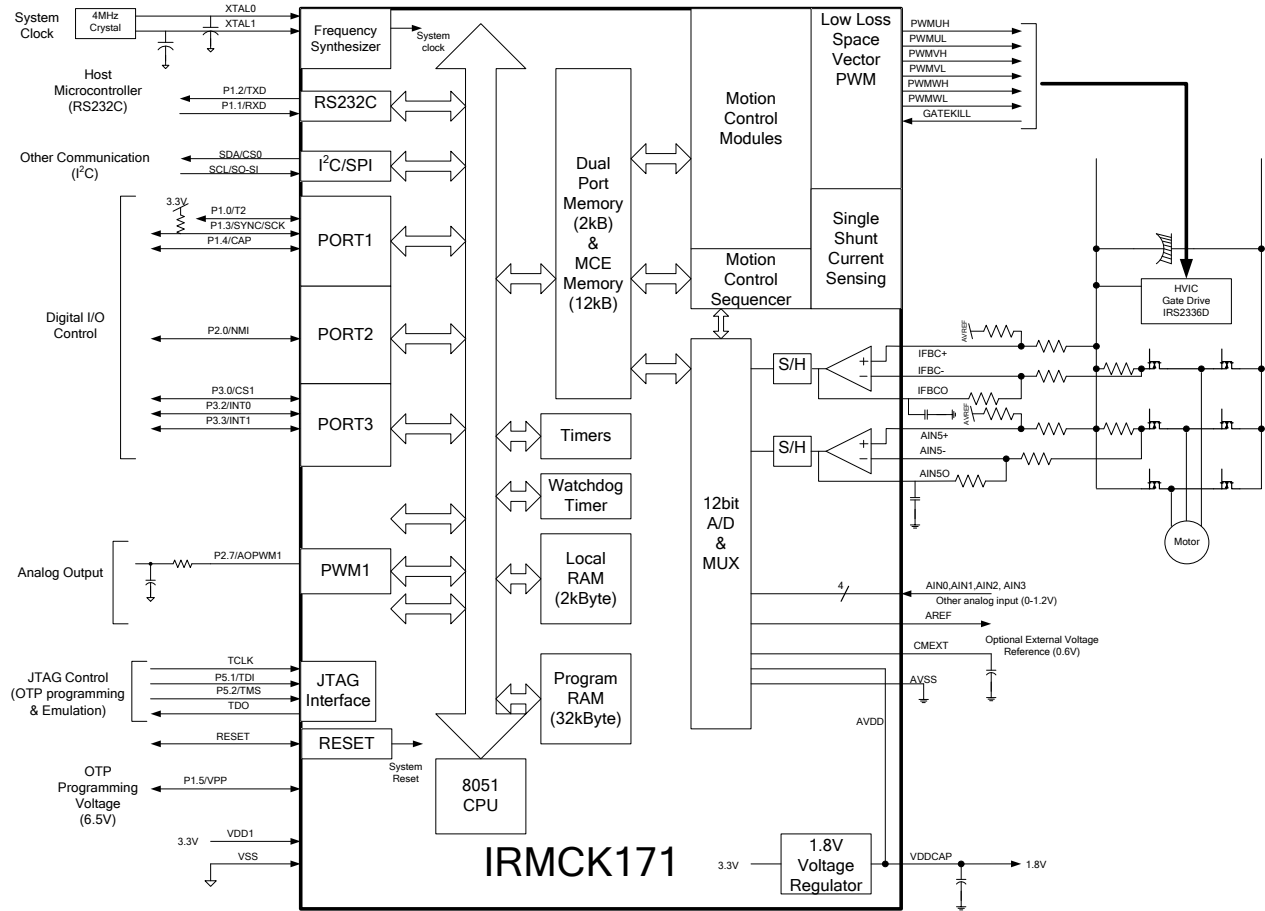


Figure 4 IRMCK171 Connection Diagram

4.1 8051 Peripheral Interface Group

UART Interface

P1.2/TXD	Output, Transmit data from IRMCK171
P1.1/RXD	Input, Receive data to IRMCK171

Discrete I/O Interface

P1.0/T2	Input/output port 1.0, can be configured as Timer/Counter 2 input
P1.1/RXD	Input/output port 1.1, can be configured as RXD input
P1.2/TXD	Input/output port 1.2, can be configured as TXD output
P1.3/SYNC/SCK	Input/output port 1.3, can be configured as SYNC output or SPI clock output, needs to be pulled up to VDD1 in order to boot from I ² C EEPROM
P1.4/CAP	Input/output port 1.4, can be configured as Capture Timer input
P1.5/VPP	Input/output port 1.5, or OTP programming voltage
P2.0/NMI	Input/output port 2.0, can be configured as non-maskable interrupt input
P3.2/INT0	Input/output port 3.2, can be configured as INT0 input
P2.7/AOPWM1	Input/output port 2.7, can be configured as AOPWM1 output
P3.0/INT2/CS1	Input/output port 3.0, can be configured as INT2 input or SPI chip select 1
P3.1/AOPWM2	Input/output port 3.1, can be configured as AOPWM2 output
P3.3/INT1	Input/output port 3.3, can be configured as INT1 input
P5.1/TDI	Input port 5.1, configured as JTAG port by default
P5.2/TMS	Input port 5.2, configured as JTAG port by default

Analog Output Interface

P2.7/AOPWM1	Input/output, can be configured as 8-bit PWM output 1 with programmable carrier frequency
P3.1/AOPWM2	Input/output, can be configured as 8-bit PWM output 2 with programmable carrier frequency

Crystal Interface

XTAL0	Input, connected to crystal
XTAL1	Output, connected to crystal

Reset Interface

RESET	Input and Output, system reset, doesn't require external RC time constant
-------	---

I²C Interface

SCL/SO-SI	Output, I ² C clock output, or SPI data
SDA/CS0	Input/output, I ² C Data line or SPI chip select 0

I²C/SPI Interface

SCL/SO-SI	Output, I ² C clock output, or SPI data
SDA/CS0	Input/output, I ² C data line or SPI chip select 0
P1.3/SYNC/SCK	Input/output port 1.3, can be configured as SYNC output or SPI clock output, needs to be pulled up to VDD1 in order to boot from I ² C EEPROM
P3.0/INT2/CS1	Input/output port 3.0, can be configured as INT2 input or SPI chip select 1

4.2 Motion Peripheral Interface Group

PWM

PWMUH	Output, PWM phase U high side gate signal, internally pulled down by 58kΩ
PWMUL	Output, PWM phase U low side gate signal, internally pulled down by 58kΩ
PWMVH	Output, PWM phase V high side gate signal, internally pulled down by 58kΩ
PWMVL	Output, PWM phase V low side gate signal, internally pulled down by 58kΩ
PWMWH	Output, PWM phase W high side gate signal, internally pulled down by 58kΩ
PWMWL	Output, PWM phase W low side gate signal, internally pulled down by 58kΩ

Fault

GATEKILL	Input, upon assertion, this negates all six PWM signals, active low, internally pulled up by 70kΩ
----------	---

4.3 Analog Interface Group

AVSS	Analog power return, (analog internal 1.8V power is shared with VDDCAP)
AREF	0.6V buffered output
CMEXT	Unbuffered 0.6V, input to the AREF buffer, capacitor needs to be connected.
IFB+	Input, Operational amplifier positive input for shunt resistor current sensing
IFB-	Input, Operational amplifier negative input for shunt resistor current sensing
IFBO	Output, Operational amplifier output for shunt resistor current sensing
AIN0	Input, Analog input channel 0 (0 – 1.2V), typically configured for DC bus voltage input
AIN1	Input, Analog input channel 1 (0 – 1.2V), needs to be pulled down to AVSS if unused
AIN2	Input, Analog input channel 2 (0 – 1.2V), needs to be pulled down to AVSS if unused
AIN3	Input, Analog input channel 3 (0 – 1.2V), needs to be pulled down to AVSS if unused
AIN4	Input, Analog input channel 4 (0 – 1.2V), needs to be pulled down to AVSS if unused
AIN5+	Input, Operational amplifier positive input for shunt resistor current sensing
AIN5-	Input, Operational amplifier negative input for shunt resistor current sensing
AIN5O	Output, Operational amplifier output for AIN5 output, there is a single sample/hold circuit on the output

4.4 Power Interface Group

VDD1	Digital power (3.3V)
VDDCAP	Internal 1.8V output, requires capacitors to the pin. Shared with analog power pad internally Note: The internal 1.8V supply is not designed to power any external circuits or devices. Only capacitors should be connected to this pin.
VSS	Digital common

4.5 Test Interface Group

P5.2/TMS	JTAG test mode input or input/output digital port
TDO	JTAG data output
P5.1/TDI	JTAG data input, or input/output digital port

TCK

JTAG test clock

5 DC Characteristics

5.1 Absolute Maximum Ratings

Symbol	Parameter	Min	Typ	Max	Condition
V _{DD1}	Supply Voltage	-0.3 V	-	3.6 V	Respect to VSS
V _{IA}	Analog Input Voltage	-0.3 V	-	1.98 V	Respect to AVSS
V _{ID}	Digital Input Voltage	-0.3 V	-	6.0 V	Respect to VSS
V _{PP}	OTP Programming voltage	-0.3V	-	7.0V	Respect to VSS
T _A	Ambient Temperature	-40 °C	-	85 °C	
T _S	Storage Temperature	-65 °C	-	150 °C	

Table 1 Absolute Maximum Ratings

Caution: Stresses beyond those listed in “Absolute Maximum Ratings” may cause permanent damage to the device. These are stress ratings only and function of the device at these or any other conditions beyond those indicated in the operational sections of the specifications are not implied.

5.2 System Clock Frequency and Power Consumption

C_{AREF} = 1nF, C_{MEXT} = 100nF. VDD1=3.3V, Unless specified, Ta = 25°C.

Symbol	Parameter	Min	Typ	Max	Unit
SYSClk	System Clock	32	-	128	MHz
P _D	Power consumption		160 ¹⁾	200	mW

Table 2 System Clock Frequency

Note 1) The value is based on the condition of MCE clock=126MHz, 8051 clock 31.5MHz with a actual motor running by a typical MCE application program and 8051 code.

5.3 Digital I/O DC Characteristics

Symbol	Parameter	Min	Typ	Max	Condition
V_{DD1}	Supply Voltage	3.0 V	3.3 V	3.6 V	Recommended
V_{PP}	OTP Programming voltage	6.70V	6.75V	6.80V	Recommended
V_{IL}	Input Low Voltage	-0.3 V	-	0.8 V	Recommended
V_{IH}	Input High Voltage	2.0 V		3.6 V	Recommended
C_{IN}	Input capacitance	-	3.6 pF	-	⁽¹⁾
I_L	Input leakage current		± 10 nA	± 1 μ A	$V_O = 3.3$ V or 0 V
$I_{OL1}^{(2)}$	Low level output current	8.9 mA	13.2 mA	15.2 mA	$V_{OL} = 0.4$ V ⁽¹⁾
$I_{OH1}^{(2)}$	High level output current	12.4 mA	24.8 mA	38 mA	$V_{OH} = 2.4$ V ⁽¹⁾
$I_{OL2}^{(3)}$	Low level output current	17.9 mA	26.3 mA	33.4 mA	$V_{OL} = 0.4$ V ⁽¹⁾
$I_{OH2}^{(3)}$	High level output current	24.6 mA	49.5 mA	81 mA	$V_{OH} = 2.4$ V ⁽¹⁾

Table 3 Digital I/O DC Characteristics

Note:

- (1) Data guaranteed by design.
- (2) Applied to SCL/SO-SI, SDA/CS0 pins.
- (3) Applied to all digital I/O pins except SCL/SO-SI and SDA/CS0 pins.

5.4 Analog I/O (IFB+,IFB-,IFBO, AIN5+,AIN5-,AIN5O) DC Characteristics

$C_{AREF} = 1\text{nF}$, $C_{MEXT} = 100\text{nF}$. $V_{DD1} = 3.3\text{V}$, Unless specified, $T_a = 25^\circ\text{C}$.

Symbol	Parameter	Min	Typ	Max	Condition
V_{OFFSET}	Input Offset Voltage	-	-	26 mV	
V_I	Input Voltage Range	0 V		1.2 V	Recommended
V_{OUTSW}	OP amp output operating range	50 mV ⁽¹⁾	-	1.2 V	
C_{IN}	Input capacitance	-	3.6 pF	-	⁽¹⁾
R_{FDBK}	OP amp feedback resistor	5 k Ω	-	20 k Ω	Requested between IFBO and IFB-
OP_{GAINCL}	Operating Close loop Gain	80 db	-	-	⁽¹⁾
CMRR	Common Mode Rejection Ratio	-	80 db	-	⁽¹⁾
I_{SRC}	Op amp output source current	-	1 mA	-	$V_{\text{OUT}} = 0.6\text{ V}$ ⁽¹⁾
I_{SNK}	Op amp output sink current	-	100 μA	-	$V_{\text{OUT}} = 0.6\text{ V}$ ⁽¹⁾

Table 4 Analog I/O DC Characteristics

Note:

(1) Data guaranteed by design.

5.5 Under Voltage Lockout DC characteristics

Unless specified, $T_a = 25^\circ\text{C}$.

Symbol	Parameter	Min	Typ	Max	Condition
UV_{CC+}	UVcc positive going Threshold	2.78 V	3.04 V	3.23 V	(1)
UV_{CC-}	UVcc negative going Threshold	2.78 V	2.97 V	3.23 V	
UV_{CCH}	UVcc Hysteresys	-	73 mV	-	(1)

Table 5 UVcc DC Characteristics

Note:

(1) Data guaranteed by design.

5.6 Itrip comparator DC characteristics

Unless specified, $V_{DD1}=3.3\text{V}$, $T_a = 25^\circ\text{C}$.

Symbol	Parameter	Min	Typ	Max	Condition
$Itrip_+$	Itrip positive going Threshold	-	1.22V	-	
$Itrip_-$	Itrip negative going Threshold	-	1.10V	-	
$ItripH$	Itrip Hysteresys	-	120mV	-	

Table 6 Itrip DC Characteristics

5.7 CMEXT and AREF Characteristics

$C_{AREF} = 1\text{nF}$, $C_{MEXT} = 100\text{nF}$. Unless specified, $T_a = 25^\circ\text{C}$.

Symbol	Parameter	Min	Typ	Max	Condition
V_{CM}	CMEXT voltage	495 mV	600 mV	700 mV	$V_{DD1} = 3.3\text{ V}^{(1)}$
V_{AREF}	Buffer Output Voltage	495 mV	600 mV	700 mV	$V_{DD1} = 3.3\text{ V}$
ΔV_o	Load regulation ($V_{DC}-0.6$)	-	1 mV	-	(1)
PSRR	Power Supply Rejection Ratio	-	75 db	-	(1)

Table 7 CMEXT and AREF DC Characteristics

Note:

(1) Data guaranteed by design.

6 AC Characteristics

6.1 Digital PLL AC Characteristics

Symbol	Parameter	Min	Typ	Max	Condition
F _{CLKIN}	Crystal input frequency	3.2 MHz	4 MHz	60 MHz	⁽¹⁾ (see figure below)
F _{PLL}	Internal clock frequency	32 MHz	50 MHz	128 MHz	⁽¹⁾
F _{LWPW}	Sleep mode output frequency	F _{CLKIN} ÷ 256	-	-	⁽¹⁾
J _S	Short time jitter	-	200 psec	-	⁽¹⁾
D	Duty cycle	-	50 %	-	⁽¹⁾
T _{LOCK}	PLL lock time	-	-	500 μsec	⁽¹⁾

Table 8 PLL AC Characteristics

Note:

(1) Data guaranteed by design.

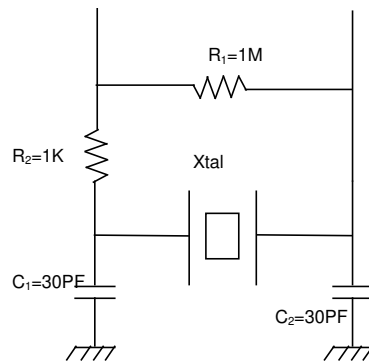


Figure 3 Crystal circuit example

6.2 Analog to Digital Converter AC Characteristics

Unless specified, $T_a = 25^\circ\text{C}$.

Symbol	Parameter	Min	Typ	Max	Condition
T_{CONV}	Conversion time	-	-	2.05 μsec	(1)
T_{HOLD}	Sample/Hold maximum hold time	-	-	10 μsec	Voltage droop ≤ 15 LSB (see figure below)

Table 9 A/D Converter AC Characteristics

Note:

(1) Data guaranteed by design.

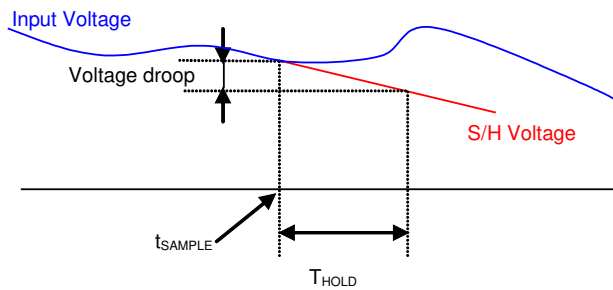


Figure 4 Voltage droop and S/H hold time

6.3 Op amp AC Characteristics

Unless specified, Ta = 25°C.

Symbol	Parameter	Min	Typ	Max	Condition
OP _{SR}	OP amp slew rate	-	10 V/μsec	-	VDD1 = 3.3 V, CL = 33 pF ⁽¹⁾
OP _{IMP}	OP input impedance	-	10 ⁸ Ω	-	⁽¹⁾ ⁽²⁾
T _{SET}	Settling time	-	400 ns	-	VDD1 = 3.3 V, CL = 33 pF ⁽¹⁾

Table 10 Current Sensing OP Amp AC Characteristics

Note:

- (1) Data guaranteed by design.
- (2) To guarantee stability of the operational amplifier, it is recommended to load the output pin by a capacitor of 47pF, see Figure 5. Here only the single shunt current amplifier is show but all op amp outputs should be loaded with this capacitor.

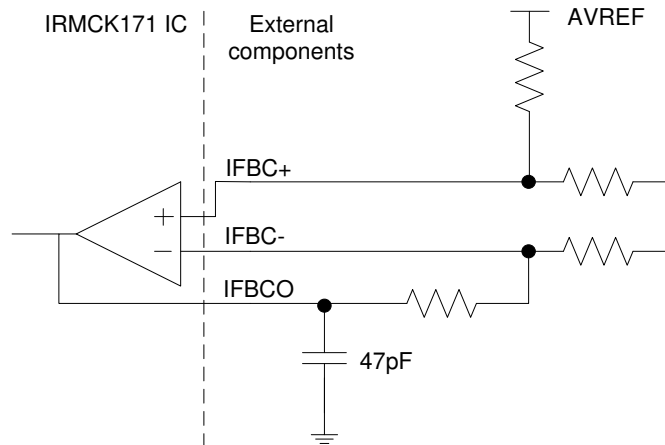


Figure 5 A capacitor of 47pF is recommended at the output pin of all op amps.

6.4 SYNC to SVPWM and A/D Conversion AC Timing

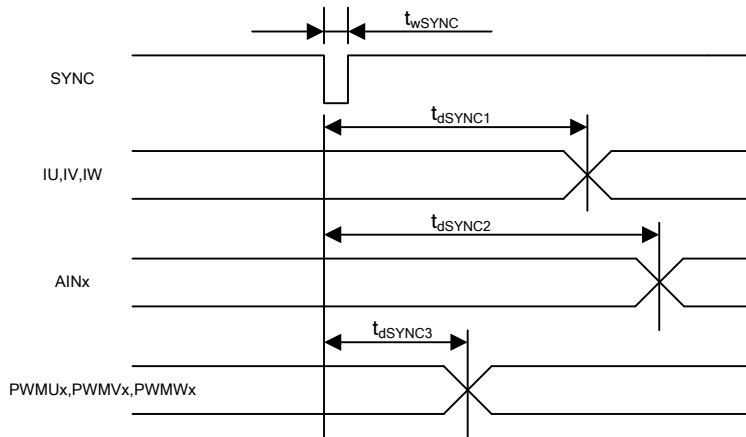


Figure 6 SYNC timing

Unless specified, Ta = 25°C.

Symbol	Parameter	Min	Typ	Max	Unit
t_{wSYNC}	SYNC pulse width	-	32	-	SYSCCLK
t_{dSYNC1}	SYNC to current feedback conversion time	-	-	100	SYSCCLK
t_{dSYNC2}	SYNC to AIN0-5 analog input conversion time	-	-	200	SYSCCLK ⁽¹⁾
t_{dSYNC3}	SYNC to PWM output delay time	-	-	2	SYSCCLK

Table 11 SYNC AC Characteristics

Note:

(1) AIN1 through AIN5 channels are converted once every 6 SYNC events

6.5 GATEKILL to SVPWM AC Timing

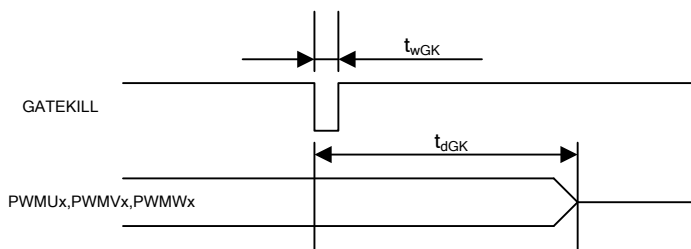


Figure 7 Gatekill timing

Unless specified, Ta = 25°C.

Symbol	Parameter	Min	Typ	Max	Unit
t _{wGK}	GATEKILL pulse width	32	-	-	SYCLK
t _{dGK}	GATEKILL to PWM output delay	-	-	100	SYCLK

Table 12 GATEKILL to SVPWM AC Timing

6.6 Itrip AC Timing

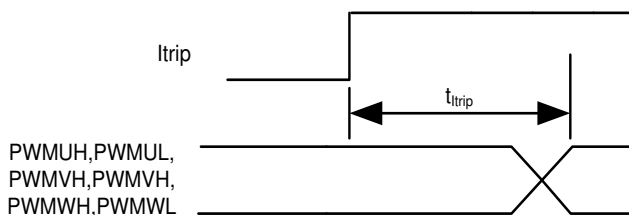


Figure 8 ITRIP timing

Unless specified, Ta = 25°C.

Symbol	Parameter	Min	Typ	Max	Unit
t _{ITRIP}	Itrip propagation delay	-	-	100(sysclk)+1.0usec	SYCLK+usec

Table 13 Itrip AC Timing

6.7 Interrupt AC Timing

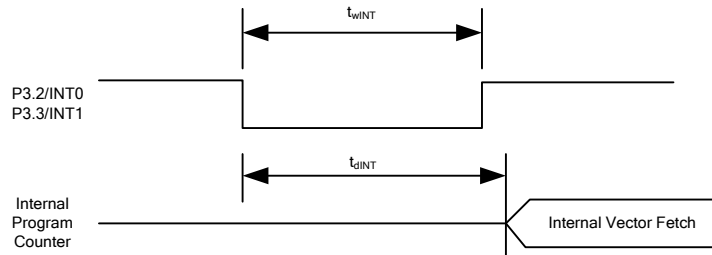


Figure 9 Interrupt timing

Unless specified, $T_a = 25^\circ\text{C}$.

Symbol	Parameter	Min	Typ	Max	Unit
t_{wINT}	INT0, INT1 Interrupt Assertion Time	4	-	-	SYSCCLK
t_{dINT}	INT0, INT1 latency	-	-	4	SYSCCLK

Table 14 Interrupt AC Timing

6.8 I²C AC Timing

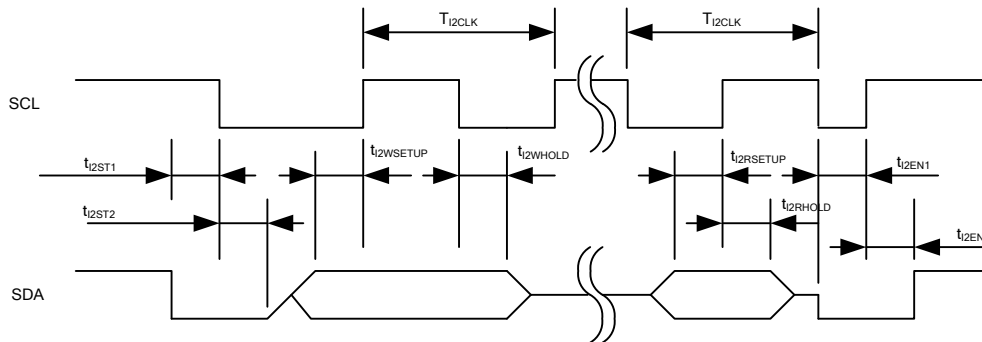


Figure 10 I²C Timing

Unless specified, $T_a = 25^\circ\text{C}$.

Symbol	Parameter	Min	Typ	Max	Unit
T_{I2CLK}	I ² C clock period	10	-	8192	SYSCCLK
t_{I2ST1}	I ² C SDA start time	0.25	-	-	T_{I2CLK}
t_{I2ST2}	I ² C SCL start time	0.25	-	-	T_{I2CLK}
$t_{I2WSETUP}$	I ² C write setup time	0.25	-	-	T_{I2CLK}
$t_{I2WHOLD}$	I ² C write hold time	0.25	-	-	T_{I2CLK}
$t_{I2RSETUP}$	I ² C read setup time	I ² C filter time ⁽¹⁾	-	-	SYSCCLK
$t_{I2RHOLD}$	I ² C read hold time	1	-	-	SYSCCLK

Table 15 I²C AC Timing

Note:

(1) I²C read setup time is determined by the programmable filter time applied to I²C communication.

6.9 SPI AC Timing

SPI Write AC timing

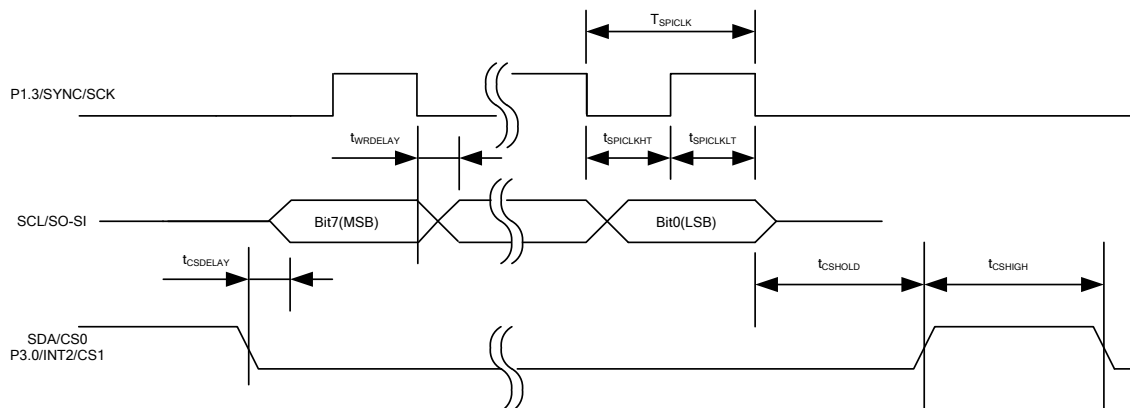
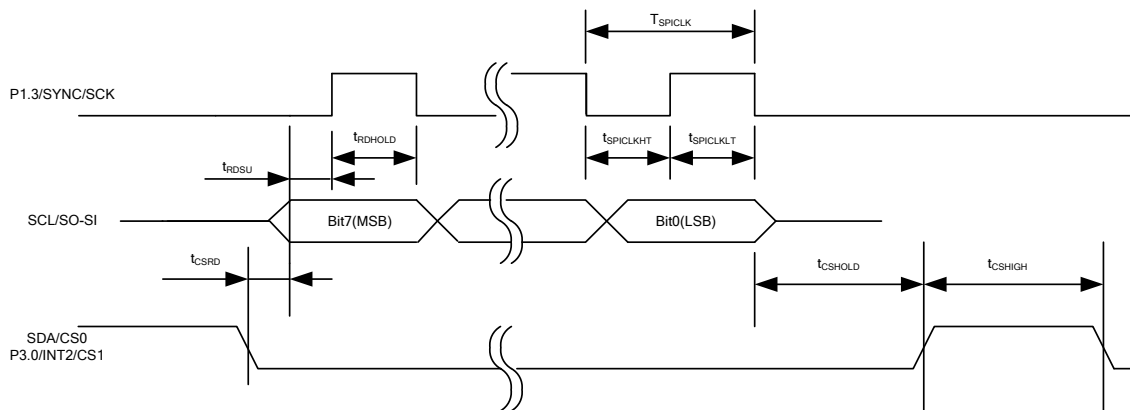


Figure 11 SPI write timing

Unless specified, $T_a = 25^\circ\text{C}$.

Symbol	Parameter	Min	Typ	Max	Unit
T_{SPICLK}	SPI clock period	4	-	-	SYSCLK
t_{SPICLKHT}	SPI clock high time	-	1/2	-	T_{SPICLK}
t_{SPICLKLT}	SPI clock low time	-	1/2	-	T_{SPICLK}
t_{CSDELAY}	CS to data delay time	-	-	10	nsec
t_{WRDELAY}	CLK falling edge to data delay time	-	-	10	nsec
t_{CSHIGH}	CS high time between two consecutive byte transfer	1	-	-	T_{SPICLK}
t_{CSHOLD}	CS hold time	-	1	-	T_{SPICLK}

Table 16 SPI Write AC Timing

SPI Read AC Timing

Figure 12 SPI read timing

 Unless specified, $T_a = 25^\circ\text{C}$.

Symbol	Parameter	Min	Typ	Max	Unit
T_{SPICLK}	SPI clock period	4	-	-	SYSCLK
t_{SPICLKHT}	SPI clock high time	-	1/2	-	T_{SPICLK}
t_{SPICLKLT}	SPI clock low time	-	1/2	-	T_{SPICLK}
t_{CSRd}	CS to data delay time	-	-	10	nsec
t_{RDSU}	SPI read data setup time	10	-	-	nsec
t_{RDHOLD}	SPI read data hold time	10	-	-	nsec
t_{CSHIGH}	CS high time between two consecutive byte transfer	1	-	-	T_{SPICLK}
t_{CSHOLD}	CS hold time	-	1	-	T_{SPICLK}

Table 17 SPI Read AC Timing

6.10 UART AC Timing

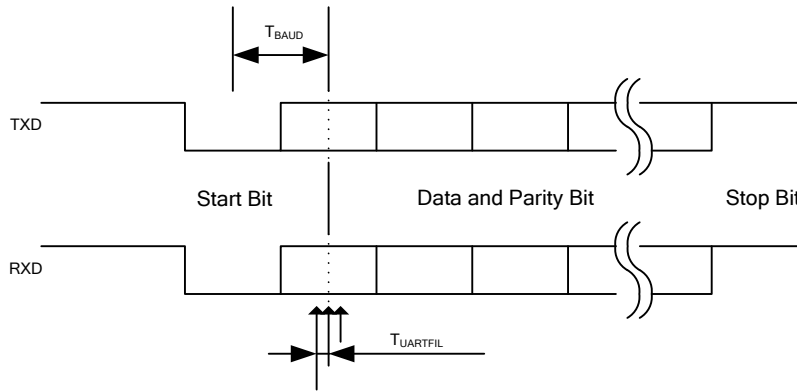


Figure 13 UART timing

Unless specified, Ta = 25°C.

Symbol	Parameter	Min	Typ	Max	Unit
T _{BAUD}	Baud Rate Period	-	57600	-	bit/sec
T _{UARTFIL}	UART sampling filter period ⁽¹⁾	-	1/16	-	T _{BAUD}

Table 18 UART AC Timing

Note:

- (1) Each bit including start and stop bit is sampled three times at center of a bit at an interval of 1/16 T_{BAUD}. If three sampled values do not agree, then UART noise error is generated.